

**RELIABILITY DATA**  
**LT1413**  
**8/21/2006**

**• OPERATING LIFE TEST**

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS <sup>(1)</sup> AT +125°C	NUMBER OF <sup>(2)</sup> FAILURES
SOIC/SOT/MSOP	50 50	9522	9522	26.40 26.40	0 0

**• HIGHLY ACCELERATED STRESS TEST AT +131°C/85%RH**

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS <sup>(4)</sup> AT +85°C	NUMBER OF FAILURES
SOIC/SOT/MSOP	200 200	9347	9534	136.00 136.00	0 0

**• PRESSURE COOKER TEST AT 15 PSIG, +121°C**

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS	NUMBER OF FAILURES
PLASTIC DIP	1,850	9336	9944	50.45	0
SOIC/SOT/MSOP	1,139 2,989	9341	0012	184.49 234.94	0 0

**• TEMP CYCLE FROM -65°C to +150°C**

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
PLASTIC DIP	100	9338	9439	10.00	0
SOIC/SOT/MSOP	300 400	9347	0012	30.10 40.10	0 0

**• THERMAL SHOCK FROM -65°C to +150°C**

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
SOIC/SOT/MSOP	200 200	9848	0012	20.00 20.00	0 0

(1) Assumes Activation Energy = 1.0 Electron Volts

(2) Failure Rate Equivalent to +55°C, 60% Confidence Level = 69.67 FITS

(3) Mean Time Between Failures in Years = 1,637

(4) Assumes 20X Acceleration from 85°C to +131°C

Note: 1 FIT = 1 Failure in One Billion Hours.